



03560.003317

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	
	:	Examiner: Unassigned
NORIO OHKUMA)	
	:	Group Art Unit: Unassigned
Application No.: 10/600,763 ✓)	
	:	
Filed: June 23, 2003)	
	:	
For: METHOD FOR MAKING)	
THROUGH-HOLE AND INK-JET	:	
PRINTER HEAD FABRICATED)	
USING THE METHOD	:	September 23, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56 and in accordance with the practice under 37 C.F.R. §§ 1.97 and 1.98, the Examiner's attention is directed to the documents listed on the enclosed Form PTO-1449. A copy of each of the listed documents is enclosed.

The Examiner's attention is also directed to the following U.S. Application, a copy of which is enclosed:

<u>Application Number</u>	<u>Inventor(s)</u>	<u>Filing Date</u>	<u>Group Art Unit</u>	<u>Status</u>
10/409,088	Norio Ohkuma	April 9, 2003	2861	Pending

Japanese Patent Application Laid-Open No. 10-181032 is discussed at pages 1 and 2 of the specification and may be relevant for the reasons discussed therein.

Japanese Patent Application Laid-Open Nos. 6-347830 and 9-11479 are discussed at page 2 of the specification and may be relevant for the reasons discussed therein.

The article entitled "Fabrication of Novel Three-Dimensional Microstructures by the Anisotropic Etching of (100) and (110) Silicon" is discussed at page 9 of the specification and may be relevant for the reasons discussed therein.

U.S. Patent No. 6,143,190 is a U.S. counterpart to Japanese Patent Application Laid-Open No. 10-181032.

U.S. Patent No. 6,128,052 is a U.S. counterpart to Japanese Patent Application Laid-Open No. 6-347830.

U.S. Patent No. 6,139,761 is a U.S. counterpart to Japanese Patent Application Laid-Open No. 9-11479.

Abstracts for Japanese Patent Application Laid-Open Nos. 10-181032, 6-347830 and 9-11479, obtained from a commercial database, are enclosed for the Examiner's convenience.

FORMAL MATTERS

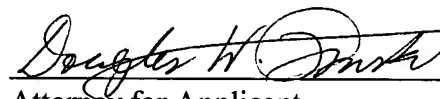
In accordance with 37 C.F.R. §1.97(b), since this Information Disclosure Statement is being filed within three months of the filing date of the subject application, neither a statement under 37 C.F.R. §1.97(e) nor payment of a fee is required for consideration of this Information Disclosure Statement.

CONCLUSION

It is respectfully requested that the above information be considered by the Examiner and that an initialed copy of the enclosed Form PTO-1449 be returned indicating that such information has been considered.

Applicant's undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,

A handwritten signature in cursive script, reading "Douglas W. Pinsky", is written over a horizontal line.

Attorney for Applicant
Douglas W. Pinsky
Registration No. 46,994

FITZPATRICK, CELLA, HARPER & SCINTO
30 Rockefeller Plaza
New York, New York 10112-3801
Facsimile: (212) 218-2200
DWP/tmc



FORM PTO 1449 (modified) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary) September 23, 2003			ATTY DOCKET NO. 03560.003317		APPLICATION NO. 10/600,763		
			APPLICANT NORIO OHKUMA				
			FILING DATE June 23, 2003		GROUP Unassigned		
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		6,113,222	09/2000	Ohkuma			
		6,128,052	10/2000	Asaba et al.			
		6,139,761	10/2000	Ohkuma			
		6,143,190	11/2000	Yagi et al.			
		6,305,080 B1	10/2001	Komuro et al.			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO/ OR ABSTRACT
		JP 10-181032	07/1998	Japan			Abstract*
		JP 6-347830	12/1994	Japan			Abstract*
		JP 9-11479	01/1997	Japan			Abstract*
OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)							
		E. Bassous, "Fabrication of Novel Three-Dimensional Microstructures by the Anisotropic Etching of (100) and (110) Silicon," IEEE Transactions on Electron Devices, October, 1978, Vol. ED-25, No. 10, pgs. 1178-1185.					
*Note: U.S. counterpart patents also submitted (see text of IDS).							
EXAMINER				DATE CONSIDERED			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicants.

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